

Complementary Darlington Power Transistor

DPAK For Surface Mount Applications

MJD128T4G (PNP)

Designed for general purpose amplifier and low speed switching applications.

Features

- Monolithic Construction With Built-in Base-Emitter Shunt Resistors
- High DC Current Gain: $h_{FE} = 2500$ (Typ) @ $I_C = 4.0$ Adc
- Epoxy Meets UL 94 V-0 @ 0.125 in.
- ESD Ratings:
 - ◆ Human Body Model, $3B > 8000$ V
 - ◆ Machine Model, $C > 400$ V
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free Devices*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V_{CEO}	120	Vdc
Collector-Base Voltage	V_{CB}	120	Vdc
Emitter-Base Voltage	V_{EB}	5	Vdc
Collector Current Continuous Peak	I_C	8 16	Adc
Base Current	I_B	120	mAdc
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	20 0.16	W W/ $^\circ\text{C}$
Total Power Dissipation* @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	1.75 0.014	W W/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	T_J, T_{stg}	-65 to +150	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	6.25	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	71.4	$^\circ\text{C}/\text{W}$

1. These ratings are applicable when surface mounted on the minimum pad sizes recommended.

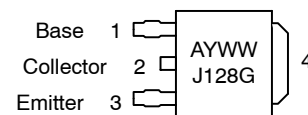
*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

SILICON
POWER TRANSISTOR
8 AMPERES
120 VOLTS, 20 WATTS



DPAK
CASE 369C
STYLE 1

MARKING DIAGRAM



A = Assembly Location
Y = Year
WW = Work Week
J128 = Device Code
G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping†
MJD128T4G	DPAK (Pb-Free)	2,500/Tape & Reel
NJVMJD128T4G	DPAK (Pb-Free)	2,500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MJD128T4G (PNP)

ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
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OFF CHARACTERISTICS

Collector-Emitter Sustaining Voltage ($I_C = 30\text{ mA}$, $I_B = 0$)	$V_{CE(sus)}$	120	–	Vdc
Collector Cutoff Current ($V_{CE} = 120\text{ Vdc}$, $I_B = 0$)	I_{CEO}	–	5	mA
Collector Cutoff Current ($V_{CB} = 100\text{ Vdc}$, $I_E = 0$)	I_{CBO}	–	10	μA
Emitter Cutoff Current ($V_{BE} = 5\text{ Vdc}$, $I_C = 0$)	I_{EBO}	–	2	mA

ON CHARACTERISTICS

DC Current Gain ($I_C = 4\text{ A}$, $V_{CE} = 4\text{ Vdc}$) ($I_C = 8\text{ A}$, $V_{CE} = 4\text{ Vdc}$)	h_{FE}	1000 100	12,000 –	–
Collector-Emitter Saturation Voltage ($I_C = 4\text{ A}$, $I_B = 16\text{ mA}$) ($I_C = 8\text{ A}$, $I_B = 80\text{ mA}$)	$V_{CE(sat)}$	– –	2 4	Vdc
Base-Emitter Saturation Voltage (1) ($I_C = 8\text{ A}$, $I_B = 80\text{ mA}$)	$V_{BE(sat)}$	–	4.5	Vdc
Base-Emitter On Voltage ($I_C = 4\text{ A}$, $V_{CE} = 4\text{ Vdc}$)	$V_{BE(on)}$	–	2.8	Vdc

DYNAMIC CHARACTERISTICS

Current-Gain-Bandwidth Product ($I_C = 3\text{ A}$, $V_{CE} = 4\text{ Vdc}$, $f = 1\text{ MHz}$)	$ h_{fe} $	4	–	MHz
Output Capacitance ($V_{CB} = 10\text{ Vdc}$, $I_E = 0$, $f = 0.1\text{ MHz}$)	C_{ob}	–	300	pF
Small-Signal Current Gain ($I_C = 3\text{ A}$, $V_{CE} = 4\text{ Vdc}$, $f = 1\text{ kHz}$)	h_{fe}	300	–	–

2. Pulse Test: Pulse Width $\leq 300\text{ }\mu\text{s}$, Duty Cycle $\leq 2\%$.

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

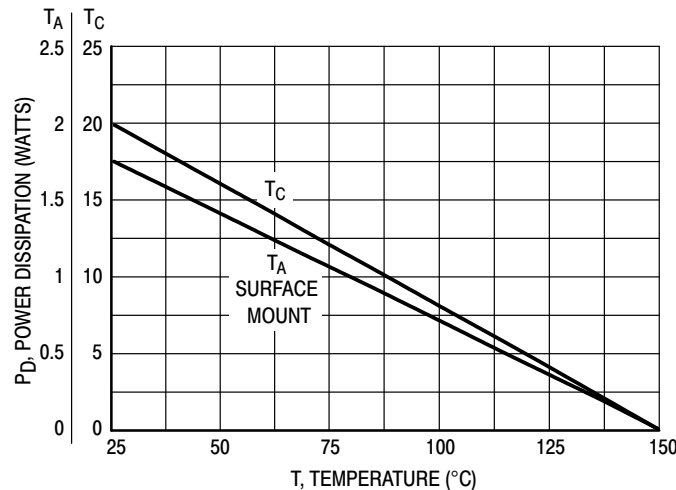


Figure 1. Power Derating

MJD128T4G (PNP)

TYPICAL ELECTRICAL CHARACTERISTICS

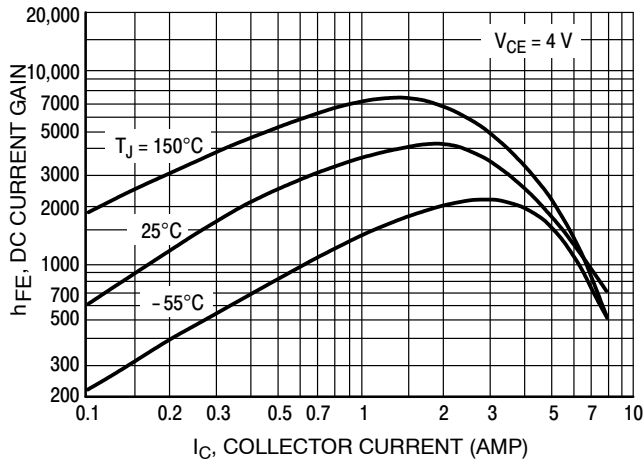


Figure 2. DC Current Gain

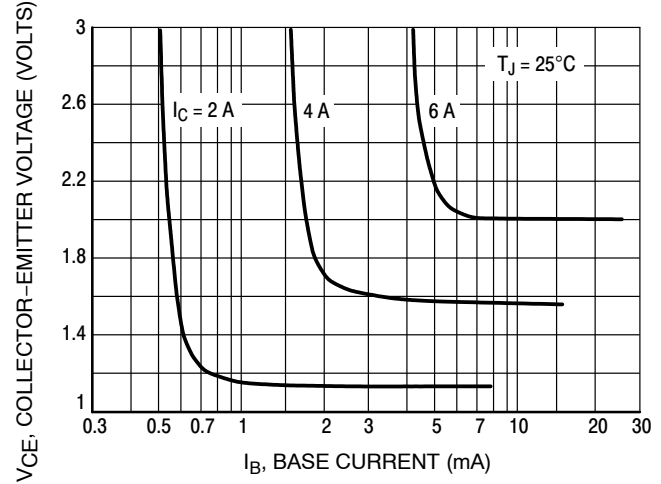


Figure 3. Collector Saturation Region

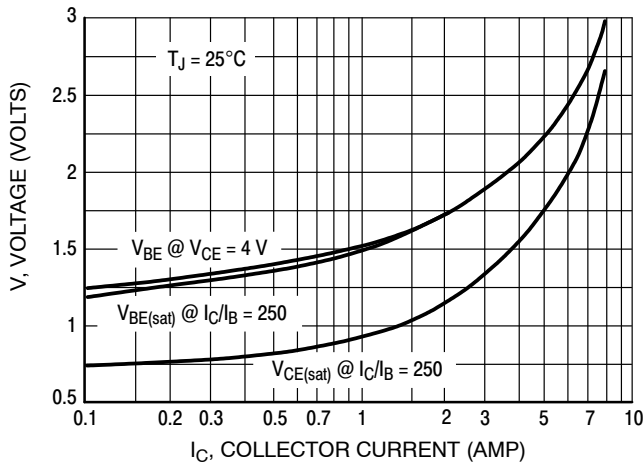


Figure 4. "On" Voltages

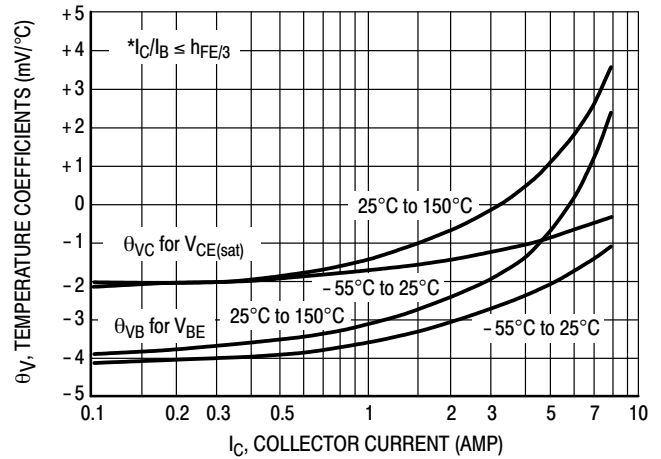


Figure 5. Temperature Coefficients

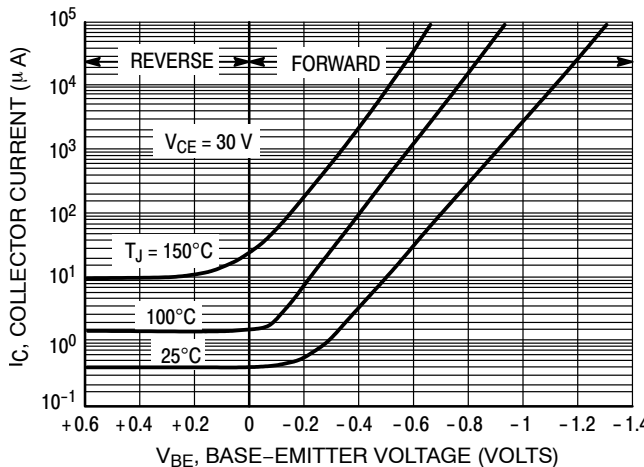


Figure 6. Collector Cut-Off Region

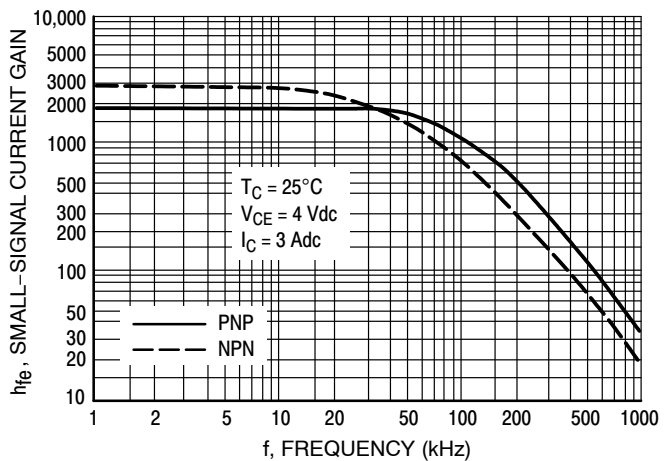


Figure 7. Small-Signal Current Gain

MJD128T4G (PNP)

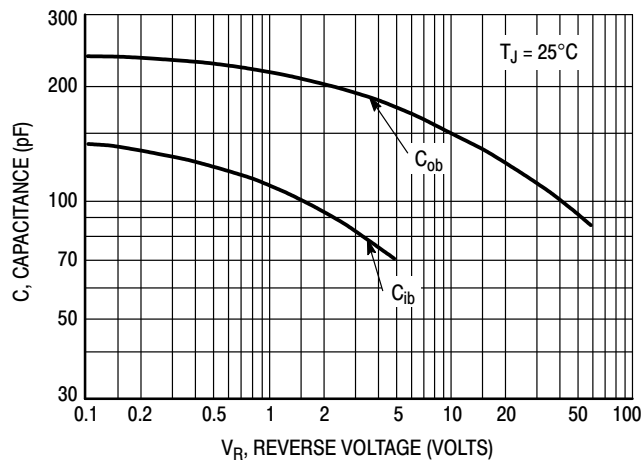


Figure 8. Capacitance

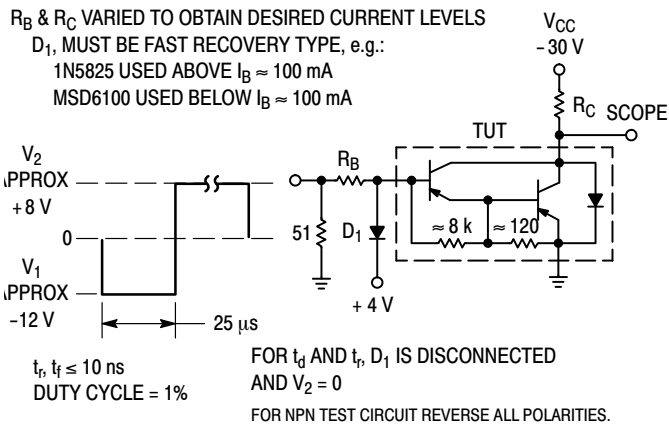


Figure 9. Switching Times Test Circuit

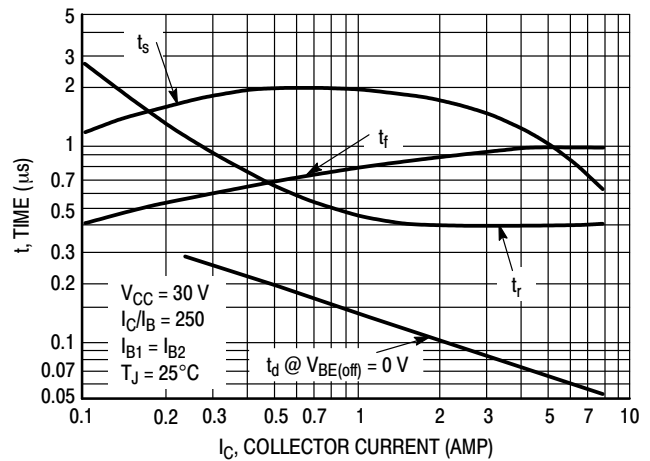


Figure 10. Switching Times

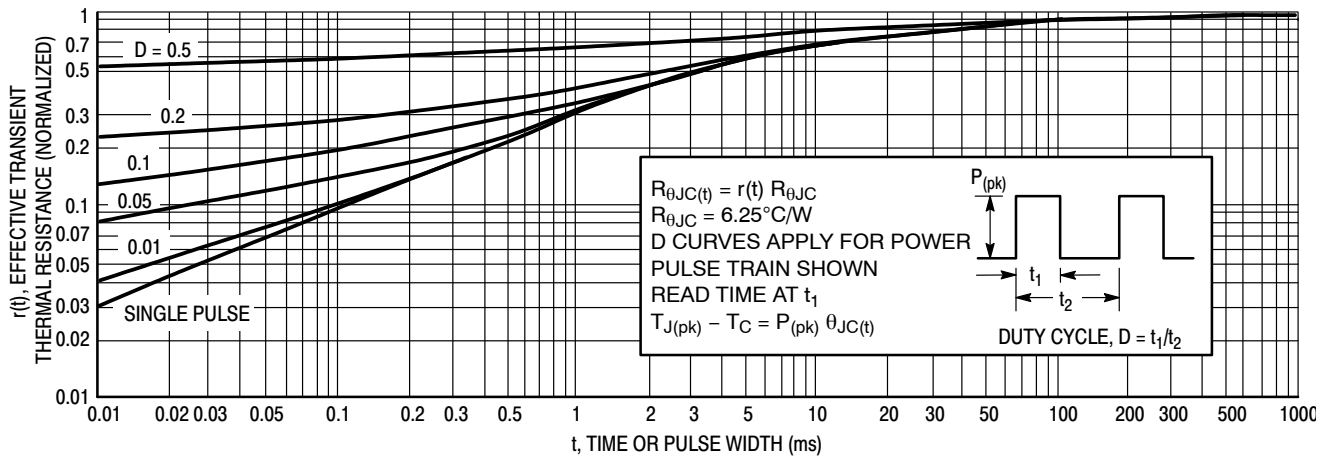


Figure 11. Thermal Response

MJD128T4G (PNP)

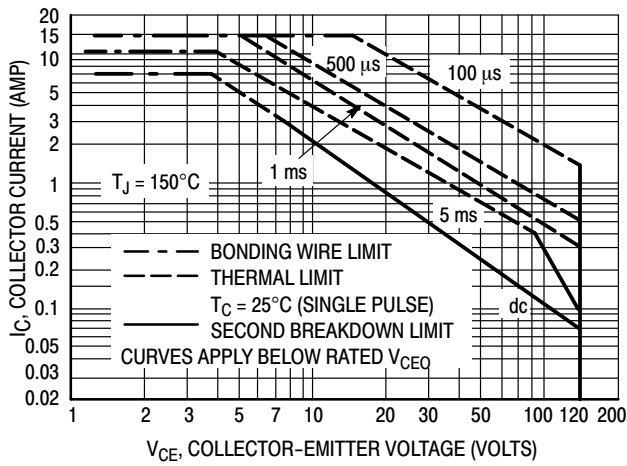


Figure 12. Maximum Forward Bias Safe Operating REA

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 12 is based on $T_{J(pk)} = 150^\circ\text{C}$; T_C is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} < 150^\circ\text{C}$. $T_{J(pk)}$ may be calculated from the data in Figure 11. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

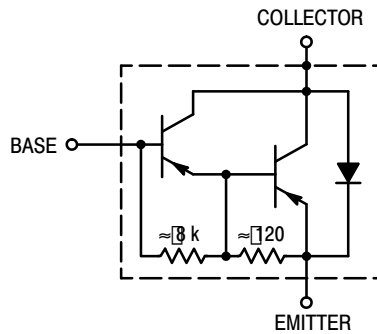


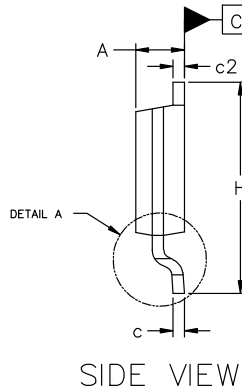
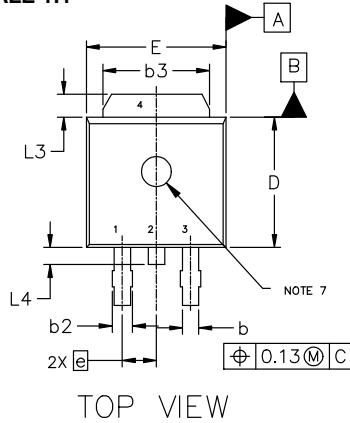
Figure 13. Darlington Schematic



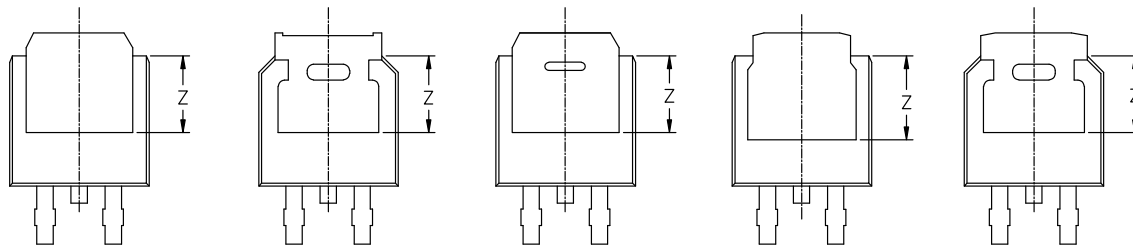
DPAK3 6.10x6.54x2.28, 2.29P
CASE 369C
ISSUE J

DATE 12 AUG 2025

SCALE 1:1



MILLIMETERS			
DIM	MIN	NOM	MAX
A	2.18	2.28	2.38
A1	0.00	---	0.13
b	0.63	0.76	0.89
b2	0.72	0.93	1.14
b3	4.57	5.02	5.46
c	0.46	0.54	0.61
c2	0.46	0.54	0.61
D	5.97	6.10	6.22
E	6.35	6.54	6.73
e	2.29 BSC		
H	9.40	9.91	10.41
L	1.40	1.59	1.78
L1	2.90 REF		
L2	0.51 BSC		
L3	0.89	---	1.27
L4	---	---	1.01
Z	3.93	---	---



NOTES:

1. DIMENSIONING AND TOLERANCING ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3, AND Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15mm PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.



RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

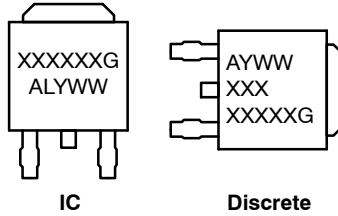
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DPAK3 6.10x6.54x2.28, 2.29P
CASE 369C
ISSUE J

DATE 12 AUG 2025

GENERIC
MARKING DIAGRAM*



XXXXXX = Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE	STYLE 4: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE	STYLE 5: PIN 1. GATE 2. ANODE 3. CATHODE 4. ANODE
STYLE 6: PIN 1. MT1 2. MT2 3. GATE 4. MT2	STYLE 7: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 8: PIN 1. N/C 2. CATHODE 3. ANODE 4. CATHODE	STYLE 9: PIN 1. ANODE 2. CATHODE 3. RESISTOR ADJUST 4. CATHODE	STYLE 10: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE

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